



## 9<sup>th</sup> MiNaPAD

Micro/Nano-Electronics Packaging & Assembly, Design and  
Manufacturing Forum

March 10-11, 2022 – Grenoble, France



### Call for extended abstracts

Extended Abstracts (2 pages typical, including graphs, pictures, ...) are requested on the following topics :

#### **Advanced packaging :**

TSVs, 2,5 & 3D interposers, wafer level packaging, embedded IC packages, SiP, PoP, MEMS packaging, power packaging, advanced substrates, PCB, Fan Out wafer and panel level processes.

#### **Assembly and manufacturing technologies:**

Bonding, advanced dicing, flux, cleaning, dispensing, coating technologies, materials & equipment related to assembly manufacturing and business aspects of the industry.

#### **Advanced interconnections:**

Flip-chip including ultra-fine pitches approaches, interconnections, IMC studies, bumping techniques (solder bumps, Cu pillars,...) disruptive interconnections, optical connections.

#### **Emerging & sustainable technologies & applications:**

Flexible/stretchable packaging, nanomaterial for interconnections, green/bio and sustainable technologies for packaging, additive manufacturing, Nano manufacturing.

#### **Innovative Materials equipment's and processes:**

3D materials, conductive & non-conductive adhesives, underfill, molding, disruptive solder alloys, thermal interface. Innovative equipment for assembly & packaging.

#### **Reliability & tests:**

Applied reliability for LED, Displays, IoT, MEMS, memories, medical devices, autonomous vehicles. Life models, failure analysis techniques & characterizations.

#### **Imaging & photonics assembly technologies:**

Assembly & packaging technologies for optical and photonics applications : imaging, displays, silicon photonics, optical sensors, high energy physics and medical imaging.

#### **Thermal/mechanical simulation and characterization:**

Components, boards & system level modelling for : interconnections, interposers, substrates, WLP & embedded packages, power modules, optical packaging, RF and MEMS.

## Practical information

### Organization :

IMAPS France

Email: [imaps.france@orange.fr](mailto:imaps.france@orange.fr)

Web: [www.france.imapseurope.org](http://www.france.imapseurope.org)

**General chair:** Alexandre VAL (VALEO)

### Technical Chairs:

Sanae BOULAY (ASML),

Jean-Luc DIOT (Assemblinnov),

Michel GARNIER (ST Microelectronics),

Romain COFFY (ST Microelectronics),

Jean-Charles SOURIAU (CEA-LETI),

Christophe ZINCK (ASE),

Gilles SIMON (CEA-LETI).



**Location :** Close to Grenoble Railway Station

WTC / Congress center

5 -7 , place Robert Schuman – BP 1521

38025 Grenoble Cedex 1

FRANCE



### Exhibition area :

Equipment & Product suppliers in the WTC Atrium during the workshop

## Important dates

### Extended abstracts submission date :

From **May 6<sup>th</sup>, 2021** to **November 28<sup>th</sup>, 2021**

Your submission must include the mailing address, business phone number and email address and the content must be without commercial information.

### Address your abstract to :

**[imaps.france@imapsfrance.org](mailto:imaps.france@imapsfrance.org)**

### Notification of acceptance :

Authors will be notified of paper acceptance with instructions for presentation **before December 10<sup>th</sup>, 2021.**

### Presentations :

Presentation should be ready one day before the workshop and supply to the chairwomen or chairmen of your session.

### Social event :

Evening dinner & visit on the 10<sup>th</sup> of March 2022



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